

Abstract of the Disclosure

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A process for recovering copper from an alkaline etch bath from an etching process in which printed boards plated with copper are etched with the alkaline etch bath and then rinsed with water, copper being removed by extraction with an organic solution, from which it is re-extracted in an acid solution. Said acid solution is passed to an operation for recovering copper, e.g. by electrolysis, but before said copper recovery a flow is diverted, in which the copper content is adjusted to a value below the value of the acid solution for copper recovery and which is used for the plating of printed boards.